

INDEMNITY BOND

This undertaking is given by Sri **Lingam Siva Surya Pavan** S/o **Sri Lingam Srinivasan** aged **20 years**, resident of **Pedapalaparru** on this the **04th December of 2024**

My son has been admitted into the B.Tech Course **Seshadri Rao Gudlavalleru Engineering College**. The participation of my son/daughter/ward in Industrial visits / Field-Works / Cocurricular and Extra-curricular activities / NCC / NSS etc., enrich his learning experience and help him in professional endeavour **and are voluntary in nature**.

In the course of participation in such of these activities the student if he sustains, injuries, etc. to the extent of endangering life of the student either the Seshadri Rao Gudlavalleru Engineering College or Concerned Industry / Organization / Corporation are not at all responsible and student and parent are not entitled for any damage or compensation or any other relief.

I / We, therefore, undertake not to claim any damage or compensation either from the college or from the concerned Industry / Organization / Corporation, in case, my son sustains any injury or involve in any untoward or unexpected mishap during the course of study/ visit / participation. We are giving this undertaking voluntarily without any force or coercion.

I / We also undertake that my son abide by the safety guidelines given by the Principal / Head of the Department and follow the instructions of accompanying faculty members, if any, during the above activities.

I myself participating in the **Smart India Hackathon (SIH)** organized by the **Ministry of Education's Innovation Cell (MoE) & All India Council of Technical Education (AICTE)** to **M. S. Ramaiah University of Applied Sciences Bangalore** with the consent of my parent from **09-12-2024 to 13-12-2024**.

1. Signature of Parent
(LINGAM SRINIVASAN)

2. Signature of Student
(LINGAM SIVA SURYA PAVAN)

Witnesses:

1)Lingam Aruna :-

2)Lingam Harika :-

Date : **04th December of 2024**

Place : Pedapalaparru